

# SN54AC374, SN74AC374 OCTAL D-TYPE EDGE-TRIGGERED FLIP-FLOPS WITH 3-STATE OUTPUTS

SCAS543E – OCTOBER 1995 - REVISED OCTOBER 2003

- 2-V to 6-V  $V_{CC}$  Operation
- Inputs Accept Voltages to 6 V
- Max  $t_{pd}$  of 9.5 ns at 5 V
- 3-State Noninverting Outputs Drive Bus Lines Directly
- Full Parallel Access for Loading

## description/ordering information

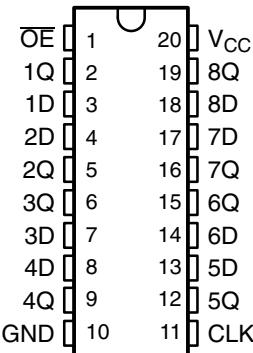
These 8-bit flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. The devices are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The eight flip-flops of the 'AC374 devices are D-type edge-triggered flip-flops. On the positive transition of the clock (CLK) input, the Q outputs are set to the logic levels set up at the data (D) inputs.

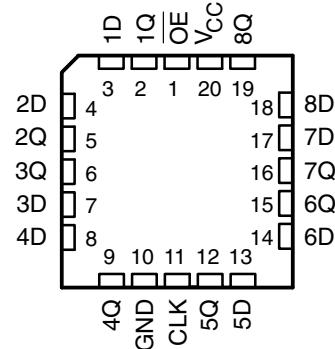
A buffered output-enable ( $OE$ ) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines in bus-organized systems without need for interface or pullup components.

$OE$  does not affect internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

SN54AC374 . . . J OR W PACKAGE  
SN74AC374 . . . DB, DW, N, NS, OR PW PACKAGE  
(TOP VIEW)



SN54AC374 . . . FK PACKAGE  
(TOP VIEW)



## ORDERING INFORMATION

$T_A$	PACKAGE <sup>†</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	PDIP – N	Tube	SN74AC374N	SN74AC374N
	SOIC – DW	Tube	SN74AC374DW	AC374
		Tape and reel	SN74AC374DWR	
	SOP – NS	Tape and reel	SN74AC374NSR	AC374
	SSOP – DB	Tape and reel	SN74AC374DBR	AC374
	TSSOP – PW	Tube	SN74AC374PW	AC374
		Tape and reel	SN74AC374PWR	
-55°C to 125°C	CDIP – J	Tube	SNJ54AC374J	SNJ54AC374J
	CFP – W	Tube	SNJ54AC374W	SNJ54AC374W
	LCCC – FK	Tube	SNJ54AC374FK	SNJ54AC374FK

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 2003, Texas Instruments Incorporated  
On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

# SN54AC374, SN74AC374 OCTAL D-TYPE EDGE-TRIGGERED FLIP-FLOPS WITH 3-STATE OUTPUTS

SCAS543E – OCTOBER 1995 - REVISED OCTOBER 2003

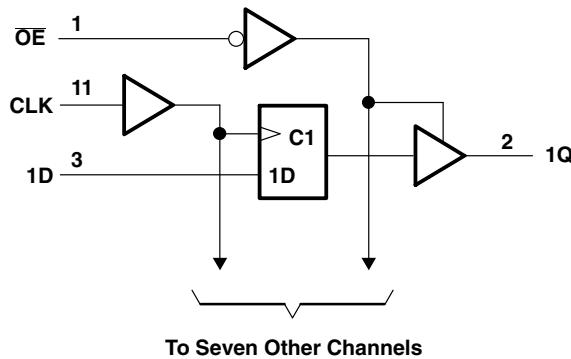
## description/ordering information (continued)

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

FUNCTION TABLE  
(each flip-flop)

INPUTS			OUTPUT
$\overline{OE}$	CLK	D	Q
L	↑	H	H
L	↑	L	L
L	H or L	X	$Q_0$
H	X	X	Z

## logic diagram (positive logic)



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, $V_{CC}$ .....	-0.5 V to 7 V
Input voltage range, $V_I$ (see Note 1) .....	-0.5 V to $V_{CC} + 0.5$ V
Output voltage range, $V_O$ (see Note 1) .....	-0.5 V to $V_{CC} + 0.5$ V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) .....	$\pm 20$ mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) .....	$\pm 20$ mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ ) .....	$\pm 50$ mA
Continuous current through $V_{CC}$ or GND .....	$\pm 200$ mA
Package thermal impedance, $\theta_{JA}$ (see Note 2):	
DB package .....	70°C/W
DW package .....	58°C/W
N package .....	69°C/W
NS package .....	60°C/W
PW package .....	83°C/W
Storage temperature range, $T_{stg}$ .....	-65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
2. The package thermal impedance is calculated in accordance with JEDEC 51-7.

**SN54AC374, SN74AC374**  
**OCTAL D-TYPE EDGE-TRIGGERED FLIP-FLOPS**  
**WITH 3-STATE OUTPUTS**

SCAS543E – OCTOBER 1995 - REVISED OCTOBER 2003

**recommended operating conditions (see Note 3)**

			SN54AC374		SN74AC374		UNIT	
			MIN	MAX	MIN	MAX		
V <sub>CC</sub>	Supply voltage			2	6	2	6	V
V <sub>IH</sub>	High-level input voltage		V <sub>CC</sub> = 3 V	2.1	2.1	2.1	V	
			V <sub>CC</sub> = 4.5 V	3.15	3.15	3.15		
			V <sub>CC</sub> = 5.5 V	3.85	3.85	3.85		
V <sub>IL</sub>	Low-level input voltage		V <sub>CC</sub> = 3 V	0.9	0.9	0.9	V	
			V <sub>CC</sub> = 4.5 V	1.35	1.35	1.35		
			V <sub>CC</sub> = 5.5 V	1.65	1.65	1.65		
V <sub>I</sub>	Input voltage			0	V <sub>CC</sub>	0	V <sub>CC</sub>	V
V <sub>O</sub>	Output voltage			0	V <sub>CC</sub>	0	V <sub>CC</sub>	V
I <sub>OH</sub>	High-level output current		V <sub>CC</sub> = 3 V	-12	-12	-12	mA	
			V <sub>CC</sub> = 4.5 V	-24	-24	-24		
			V <sub>CC</sub> = 5.5 V	-24	-24	-24		
I <sub>OL</sub>	Low-level output current		V <sub>CC</sub> = 3 V	12	12	12	mA	
			V <sub>CC</sub> = 4.5 V	24	24	24		
			V <sub>CC</sub> = 5.5 V	24	24	24		
Δt/Δv	Input transition rise or fall rate			8	8	8	ns/V	
T <sub>A</sub>	Operating free-air temperature			-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			SN54AC374	SN74AC374	UNIT
			MIN	TYP	MAX	MIN	MAX	
V <sub>OH</sub>	I <sub>OH</sub> = -50 μA	3 V	2.9		2.9	2.9	2.9	V
		4.5 V	4.4		4.4	4.4	4.4	
		5.5 V	5.4		5.4	5.4	5.4	
	I <sub>OH</sub> = -12 mA	3 V	2.56		2.4	2.46	2.46	
		4.5 V	3.86		3.7	3.76	3.76	
		5.5 V	4.86		4.7	4.76	4.76	
V <sub>OL</sub>	I <sub>OL</sub> = 50 μA	3 V		0.1		0.1	0.1	V
		4.5 V		0.1		0.1	0.1	
		5.5 V		0.1		0.1	0.1	
	I <sub>OL</sub> = 12 mA	3 V		0.36		0.5	0.44	
		4.5 V		0.36		0.5	0.44	
		5.5 V		0.36		0.5	0.44	
I <sub>I</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	5.5 V		±0.1		±1	±1	μA
I <sub>OZ</sub>	V <sub>O</sub> = V <sub>CC</sub> or GND	5.5 V		±0.25		±5	±2.5	μA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	5.5 V		4		80	40	μA
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	5 V		4.5				pF

**SN54AC374, SN74AC374  
OCTAL D-TYPE EDGE-TRIGGERED FLIP-FLOPS  
WITH 3-STATE OUTPUTS**

SCAS543E – OCTOBER 1995 - REVISED OCTOBER 2003

**timing requirements over recommended operating free-air temperature range,  $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$  (unless otherwise noted) (see Figure 1)**

		$T_A = 25^\circ\text{C}$			SN54AC374		SN74AC374		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	
$f_{clock}$	Clock frequency			60		60		60	MHz
$t_w$	Pulse duration, CLK high or low			5.5		6.5		6	ns
$t_{su}$	Setup time, data before CLK↑			5.5		6.5		6	ns
$t_h$	Hold time, data after CLK↑			1		1		1	ns

**timing requirements over recommended operating free-air temperature range,  $V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$  (unless otherwise noted) (see Figure 1)**

		$T_A = 25^\circ\text{C}$			SN54AC374		SN74AC374		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	
$f_{clock}$	Clock frequency			100		95		100	MHz
$t_w$	Pulse duration, CLK high or low			4		5		4.5	ns
$t_{su}$	Setup time, data before CLK↑			4		5		4.5	ns
$t_h$	Hold time, data after CLK↑			1.5		1.5		1.5	ns

**switching characteristics over recommended operating free-air temperature range,  $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$  (unless otherwise noted) (see Figure 1)**

PARAMETER	TO (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			SN54AC374		SN74AC374		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$f_{max}$			60	110		60		60		MHz
$t_{PLH}$	CLK	Q	3	11	13.5	3	16.5	1.5	15.5	ns
$t_{PHL}$			2.5	10	12.5	3	15	2	14	
$t_{PZH}$	$\overline{OE}$	Q	3	9.5	11.5	1	14	1.5	13	ns
$t_{PZL}$			3.5	9	11.5	1	14	1.5	13	
$t_{PHZ}$	$\overline{OE}$	Q	3	10.5	12.5	1	16	2	14.5	ns
$t_{PLZ}$			2	8	11.5	1	13	1	12.5	

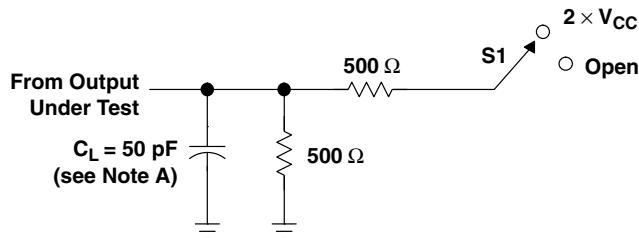
**switching characteristics over recommended operating free-air temperature range,  $V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$  (unless otherwise noted) (see Figure 1)**

PARAMETER	TO (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			SN54AC374		SN74AC374		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$f_{max}$			100	155		95		100		MHz
$t_{PLH}$	CLK	Q	2.5	8	9.5	3	12	1.5	10.5	ns
$t_{PHL}$			2	7	9	3	11	1.5	10	
$t_{PZH}$	$\overline{OE}$	Q	2	7	8.5	1.5	10	1	9.5	ns
$t_{PZL}$			2	6.5	8.5	1.5	10.5	1	9.5	
$t_{PHZ}$	$\overline{OE}$	Q	2	8	11	1.5	12.5	2	12.5	ns
$t_{PLZ}$			1.5	6.5	8.5	1.5	10.5	1	10	

**operating characteristics,  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^\circ\text{C}$**

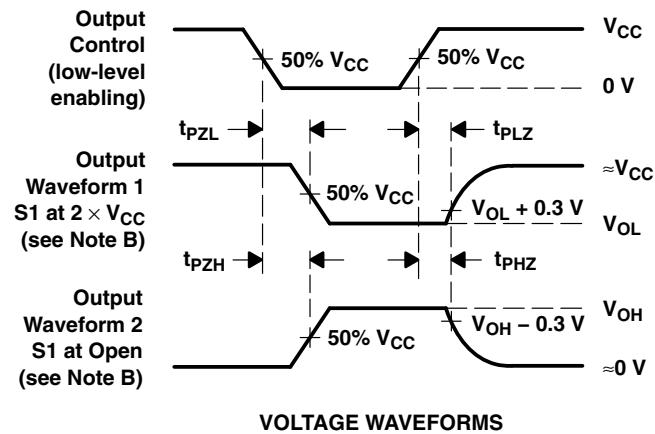
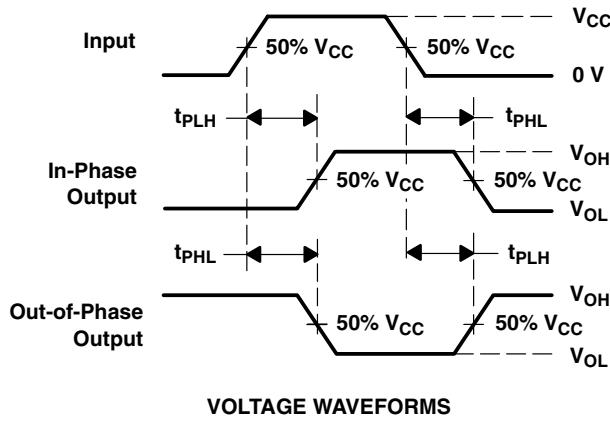
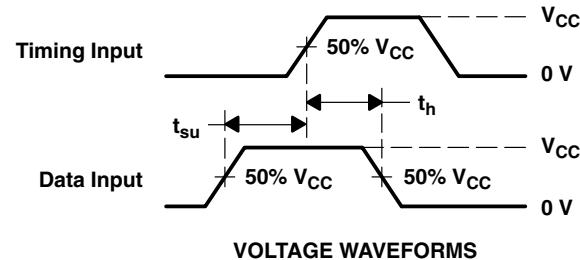
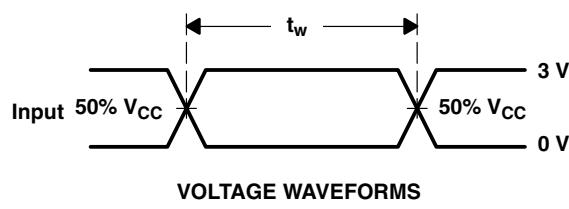
PARAMETER	TEST CONDITIONS	TYP	UNIT
$C_{pd}$ Power dissipation capacitance	$C_L = 50 \text{ pF}$ , $f = 1 \text{ MHz}$	40	$\text{pF}$

PARAMETER MEASUREMENT INFORMATION



TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	2 $\times$ $V_{CC}$
$t_{PHZ}/t_{PZH}$	Open

LOAD CIRCUIT



NOTES:

- $C_L$  includes probe and jig capacitance.
- Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5 \text{ ns}$ ,  $t_f \leq 2.5 \text{ ns}$ .
- The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-87694012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962-87694012A SNJ54AC374FK	<a href="#">Samples</a>
5962-8769401RA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8769401RA SNJ54AC374J	<a href="#">Samples</a>
5962-8769401SA	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	5962-8769401SA SNJ54AC374W	<a href="#">Samples</a>
5962-8769401VRA	ACTIVE	CDIP	J	20	20	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8769401VR A SNV54AC374J	<a href="#">Samples</a>
5962-8769401VSA	ACTIVE	CFP	W	20	25	TBD	Call TI	N / A for Pkg Type	-55 to 125	5962-8769401VS A SNV54AC374W	<a href="#">Samples</a>
SN74AC374DBLE	OBsolete	SSOP	DB	20		TBD	Call TI	Call TI	-40 to 85		
SN74AC374DBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC374	<a href="#">Samples</a>
SN74AC374DBRE4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC374	<a href="#">Samples</a>
SN74AC374DBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC374	<a href="#">Samples</a>
SN74AC374DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC374	<a href="#">Samples</a>
SN74AC374DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC374	<a href="#">Samples</a>
SN74AC374DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC374	<a href="#">Samples</a>
SN74AC374DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC374	<a href="#">Samples</a>
SN74AC374DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC374	<a href="#">Samples</a>
SN74AC374DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC374	<a href="#">Samples</a>
SN74AC374N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74AC374N	<a href="#">Samples</a>

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AC374NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74AC374N	<a href="#">Samples</a>
SN74AC374NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC374	<a href="#">Samples</a>
SN74AC374NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC374	<a href="#">Samples</a>
SN74AC374NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC374	<a href="#">Samples</a>
SN74AC374PW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC374	<a href="#">Samples</a>
SN74AC374PWE4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC374	<a href="#">Samples</a>
SN74AC374PWG4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC374	<a href="#">Samples</a>
SN74AC374PWLE	OBsolete	TSSOP	PW	20		TBD	Call TI	Call TI	-40 to 85		
SN74AC374PWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC374	<a href="#">Samples</a>
SN74AC374PWRE4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC374	<a href="#">Samples</a>
SN74AC374PWRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC374	<a href="#">Samples</a>
SNJ54AC374FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962-87694012A SNJ54AC374FK	<a href="#">Samples</a>
SNJ54AC374J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8769401RA SNJ54AC374J	<a href="#">Samples</a>
SNJ54AC374W	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	5962-8769401SA SNJ54AC374W	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

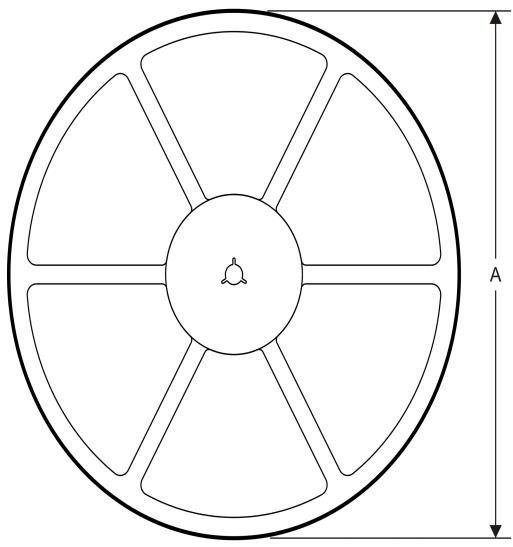
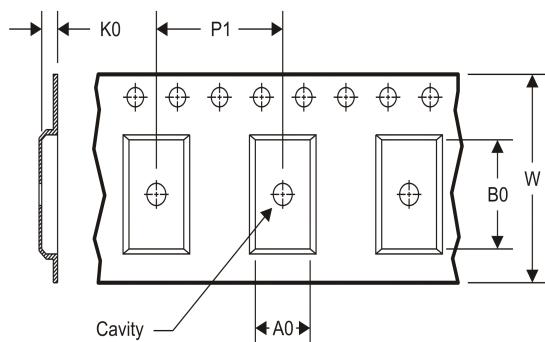
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF SN54AC374, SN54AC374-SP, SN74AC374 :**

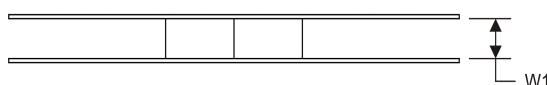
- Catalog: [SN74AC374](#), [SN54AC374](#)
- Military: [SN54AC374](#)
- Space: [SN54AC374-SP](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers


**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AC374DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74AC374DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74AC374NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1
SN74AC374PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**

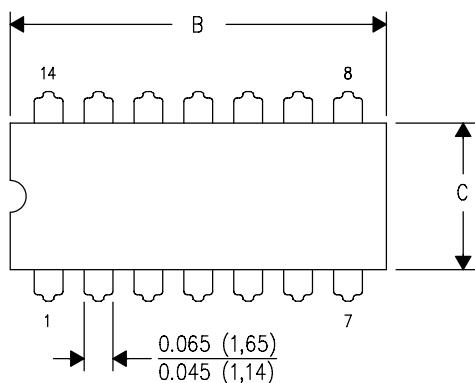

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AC374DBR	SSOP	DB	20	2000	367.0	367.0	38.0
SN74AC374DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74AC374NSR	SO	NS	20	2000	367.0	367.0	45.0
SN74AC374PWR	TSSOP	PW	20	2000	367.0	367.0	38.0

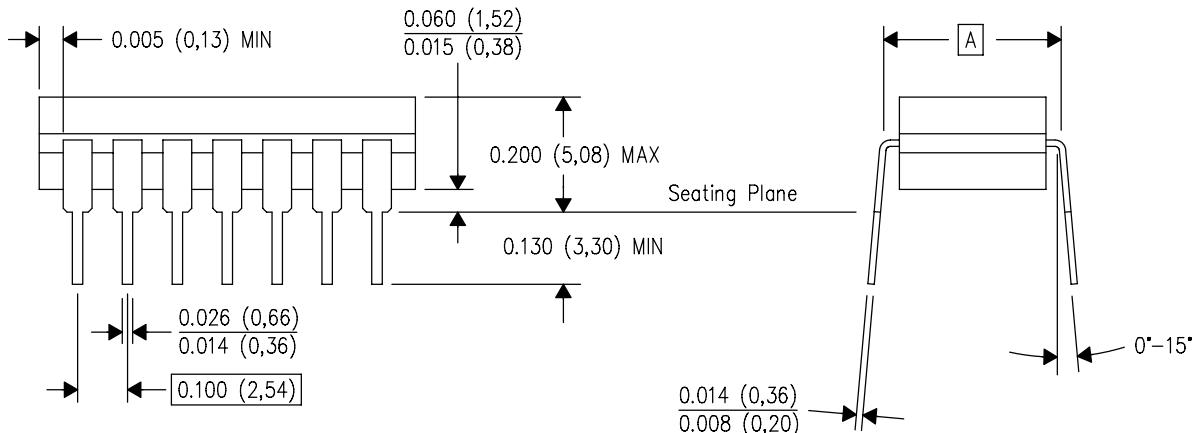
J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

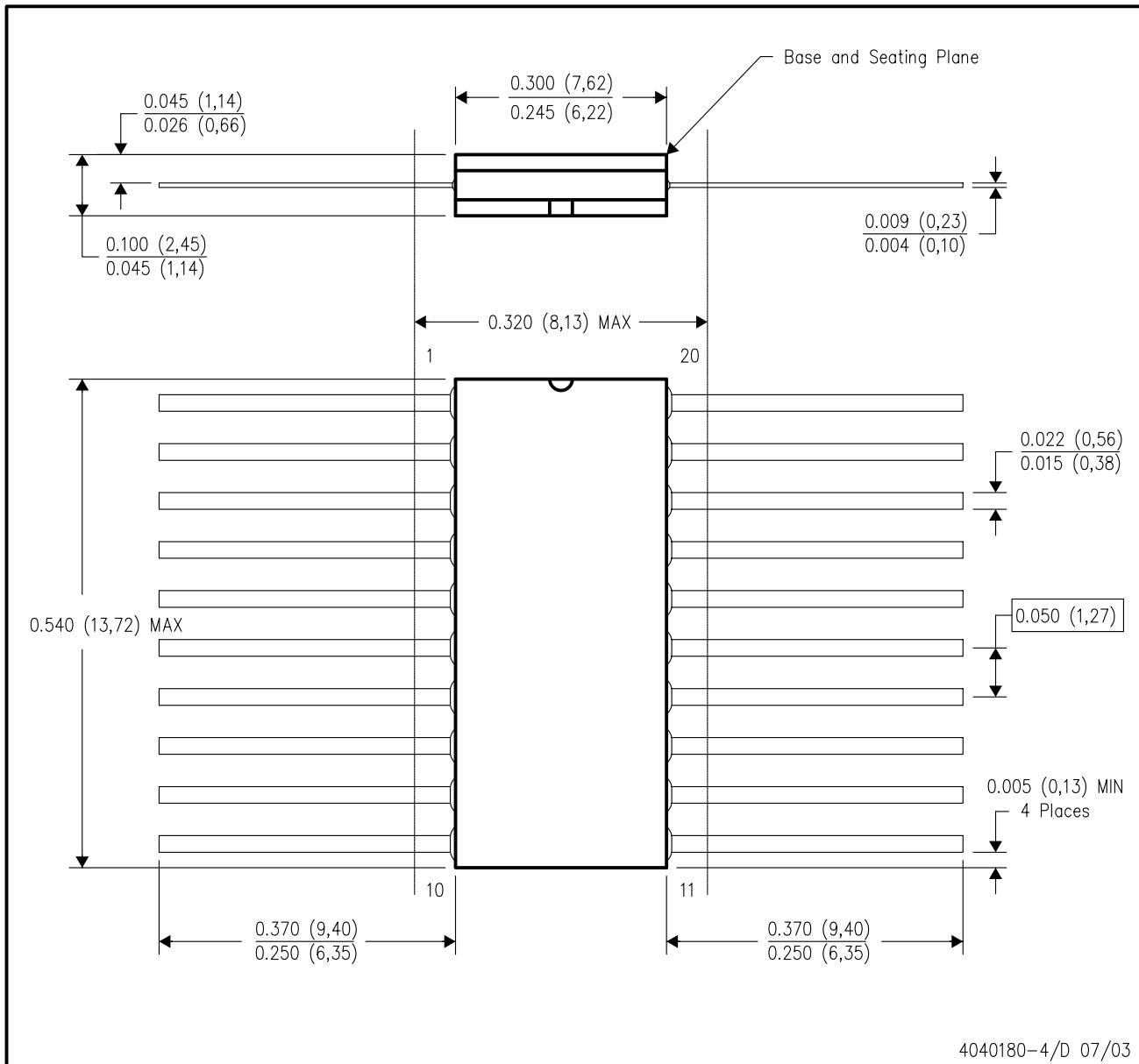


4040083/F 03/03

NOTES: A. All linear dimensions are in inches (millimeters).  
B. This drawing is subject to change without notice.  
C. This package is hermetically sealed with a ceramic lid using glass frit.  
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.  
E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



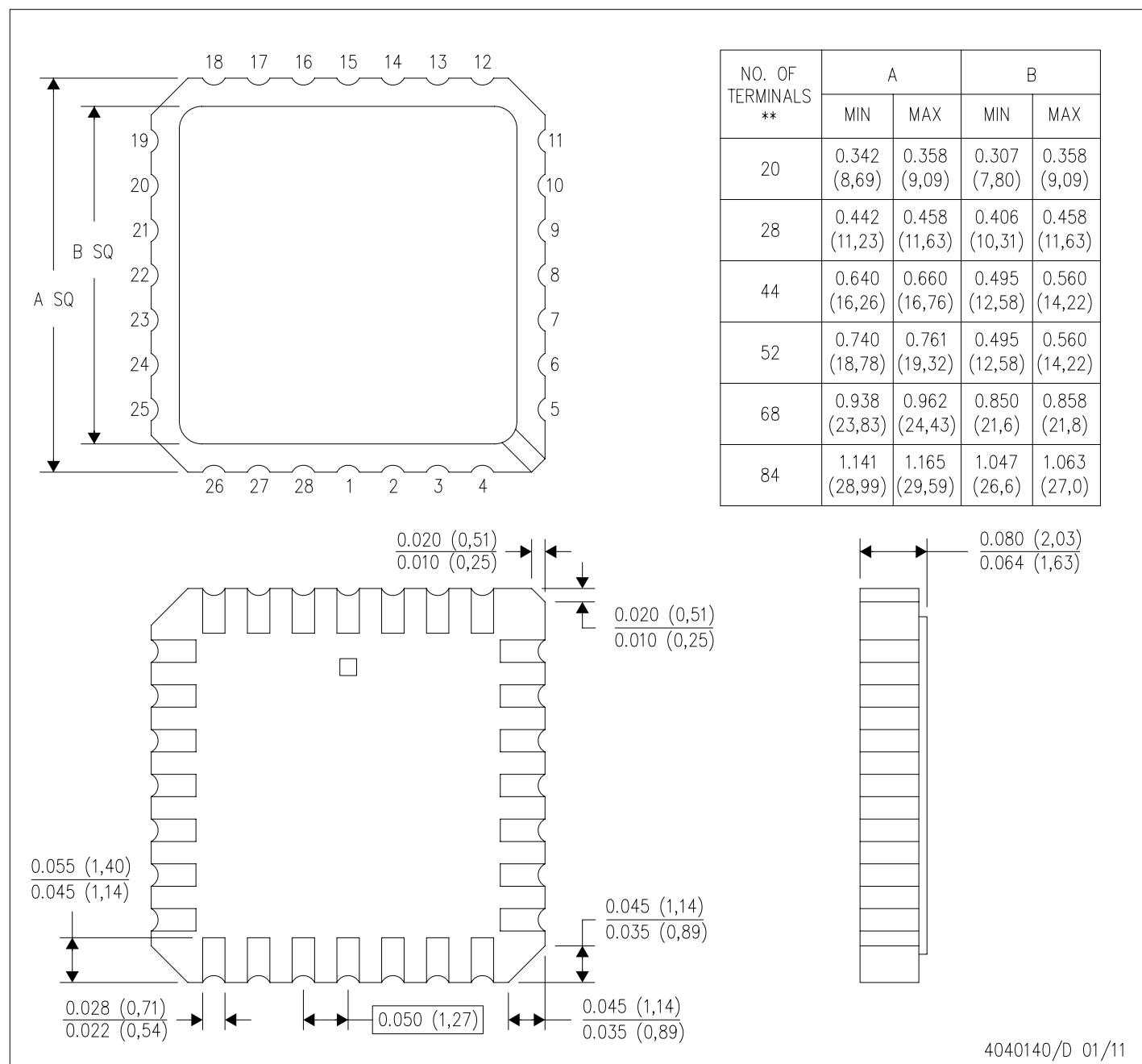
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within Mil-Std 1835 GDFP2-F20

FK (S-CQCC-N\*\*)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES:

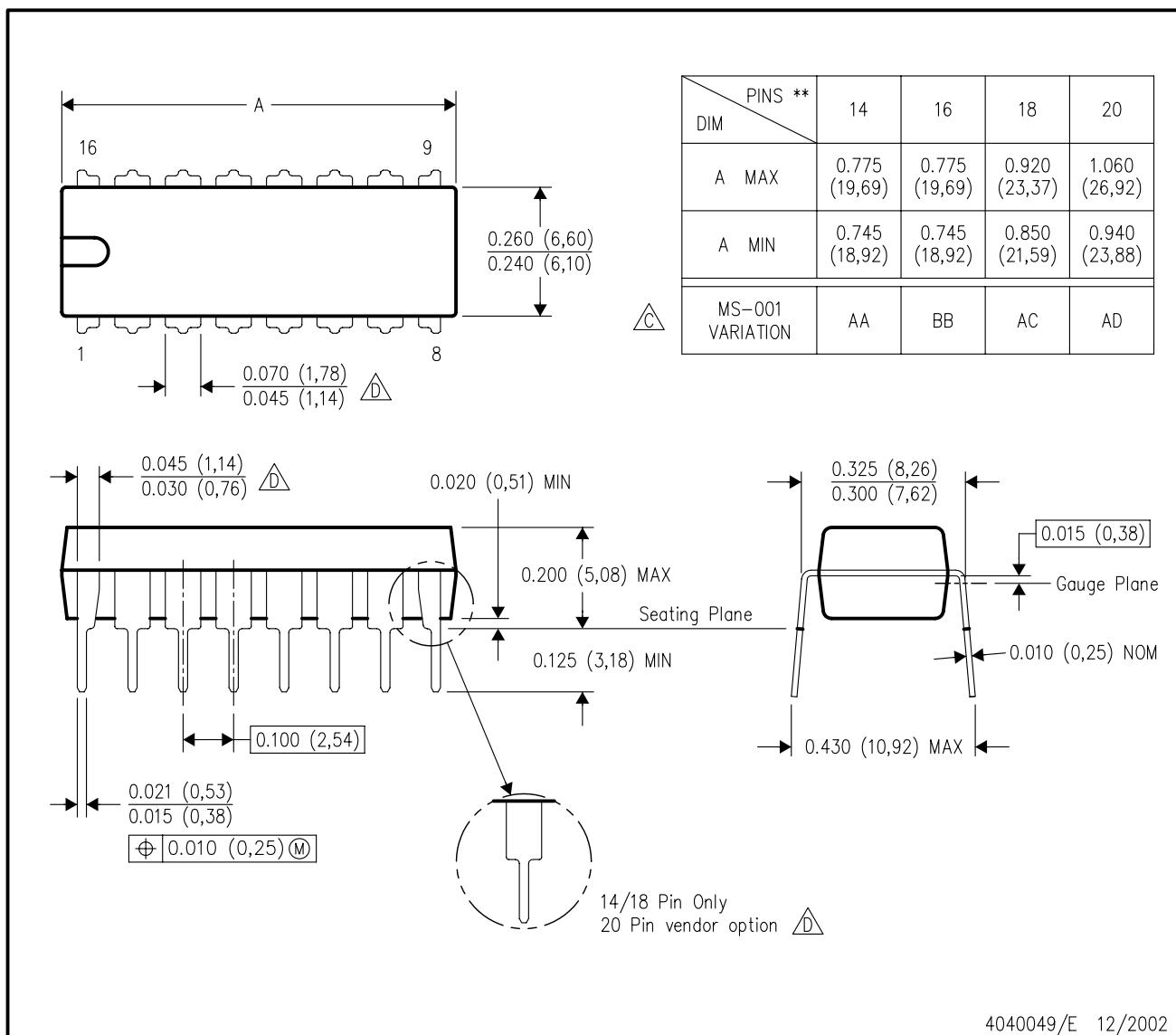
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004

4040140/D 01/11

## N (R-PDIP-T\*\*)

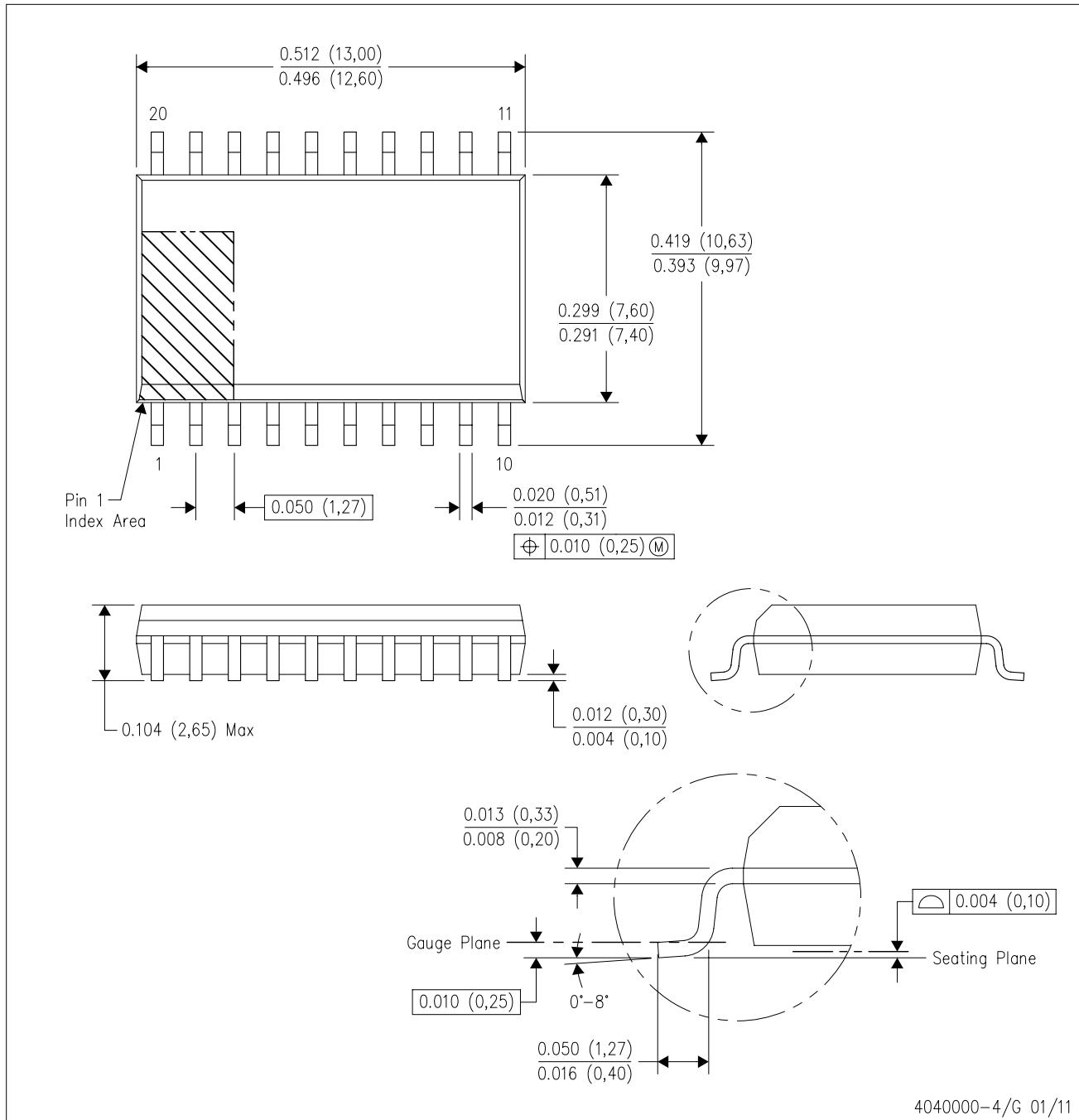
16 PINS SHOWN

## PLASTIC DUAL-IN-LINE PACKAGE



DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE

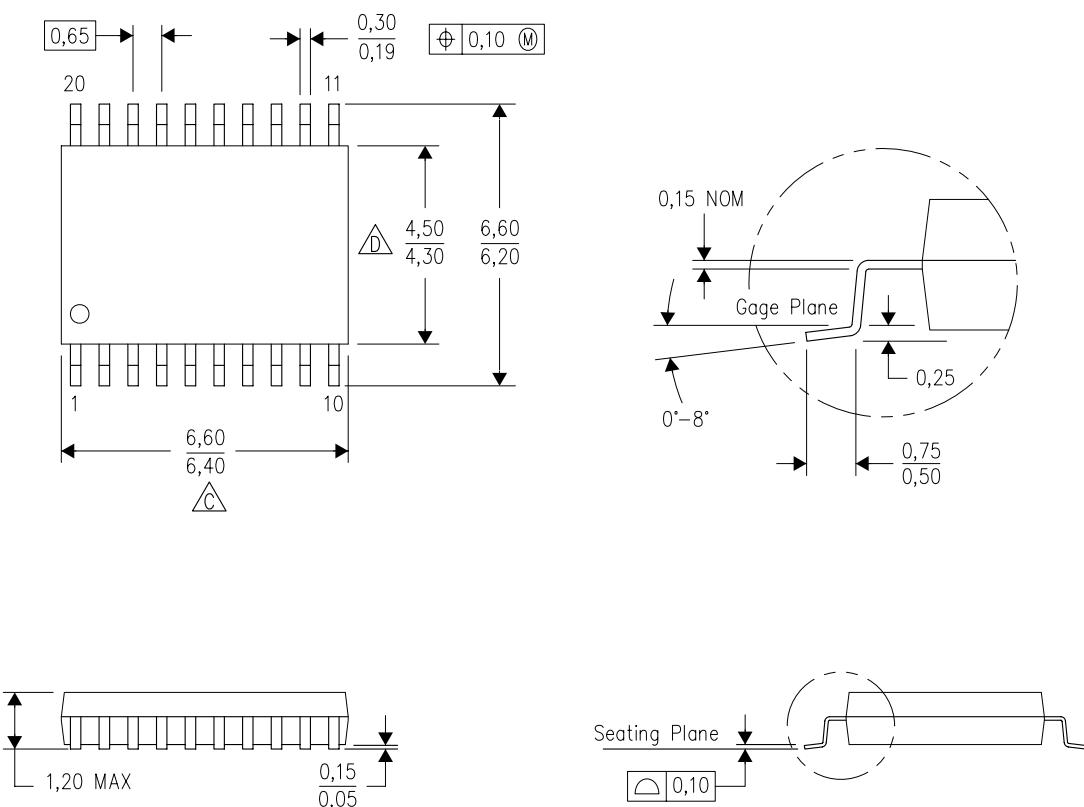


NOTES:

- All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0.15).
- Falls within JEDEC MS-013 variation AC.

PW (R-PDSO-G20)

## PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

 Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 each side.

 Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.

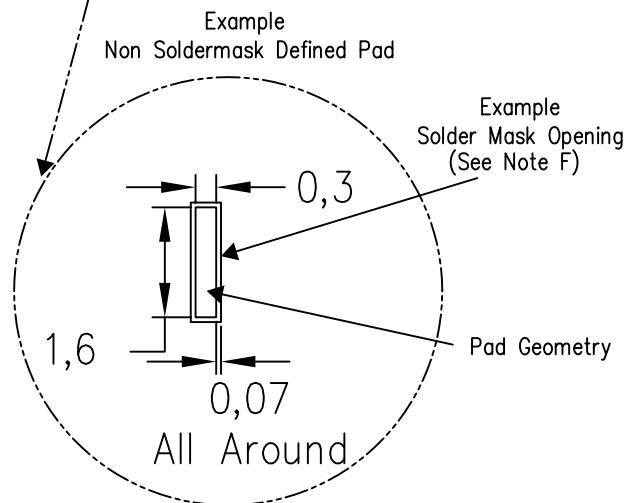
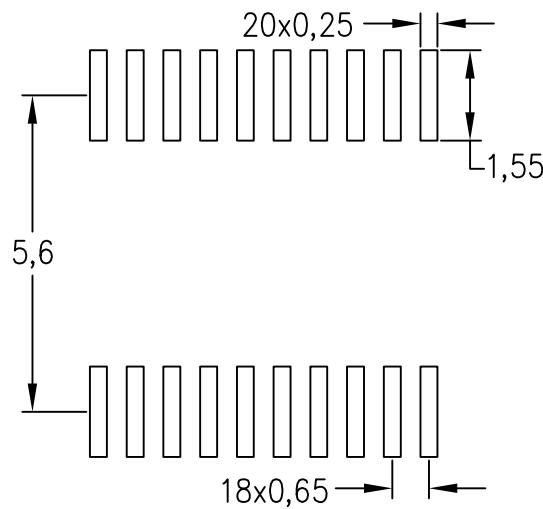
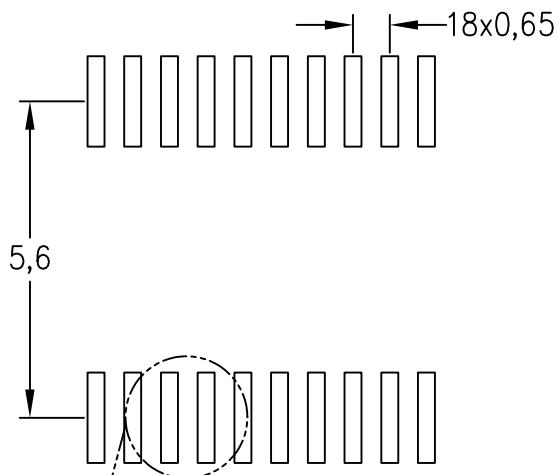
E. Falls within JFDEC M0-153

## PW (R-PDSO-G20)

## PLASTIC SMALL OUTLINE

## Example Board Layout

Based on a stencil thickness  
of .127mm (.005inch).



4211284-5/F 12/12

NOTES:

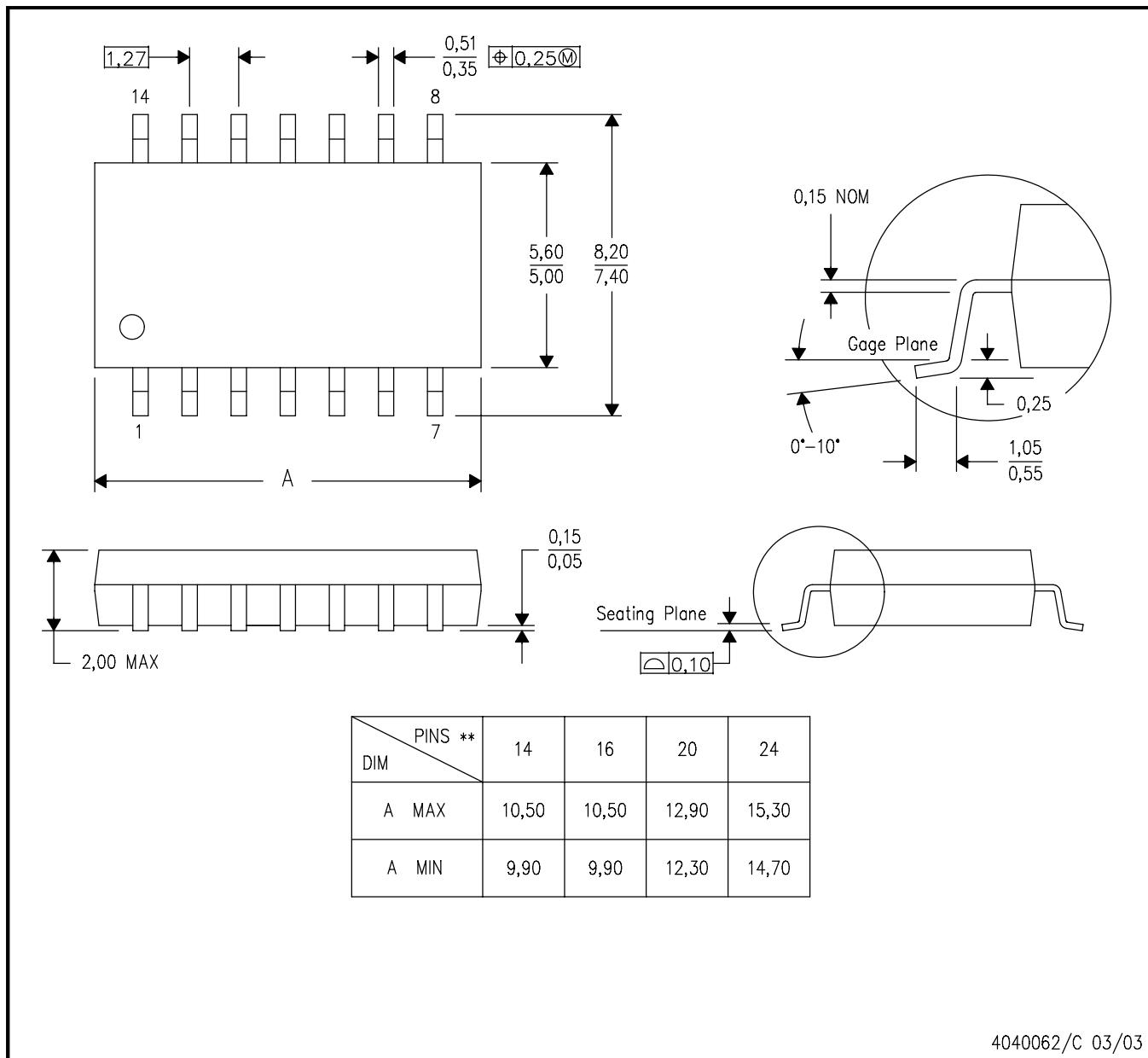
- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Publication IPC-7351 is recommended for alternate design.
- Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

## MECHANICAL DATA

**NS (R-PDSO-G\*\*)**

## PLASTIC SMALL-OUTLINE PACKAGE

**14-PINS SHOWN**



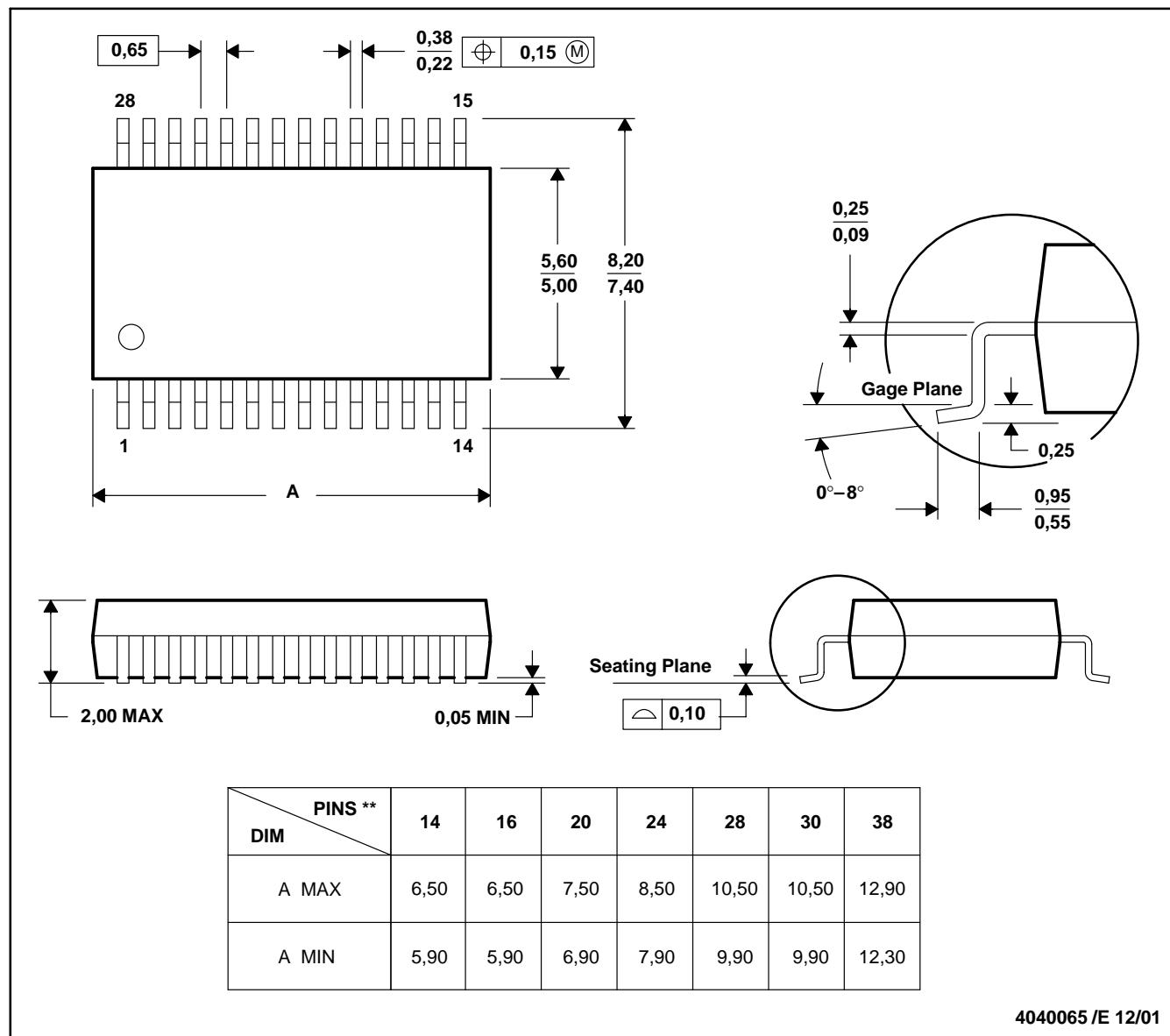
NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

## DB (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products	Applications
Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>
DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>
OMAP Applications Processors	<a href="http://www.ti.com/omap">www.ti.com/omap</a>
Wireless Connectivity	<a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a>
	<b>TI E2E Community</b>
	<a href="http://e2e.ti.com">e2e.ti.com</a>